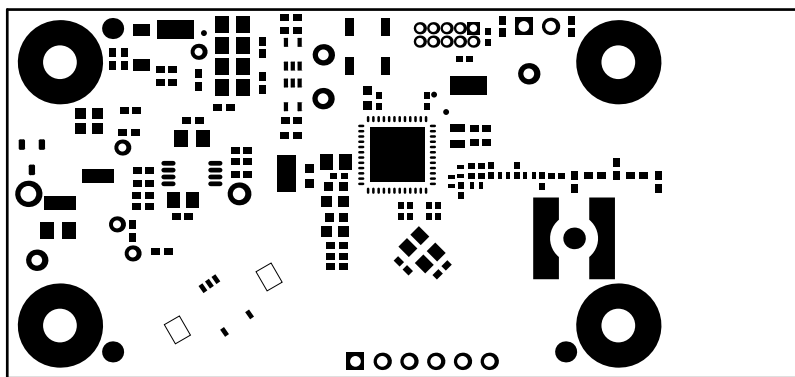
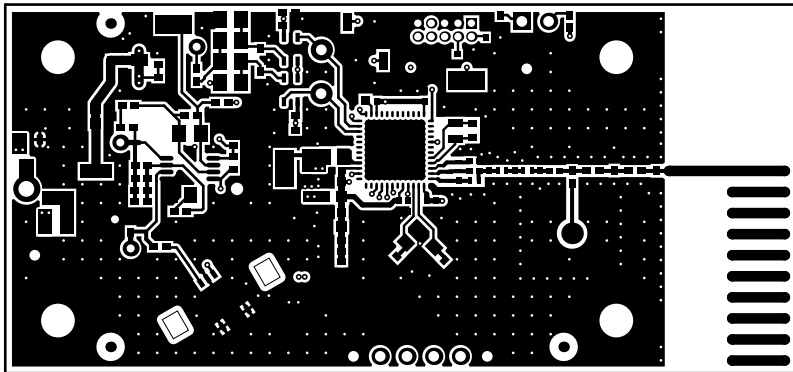


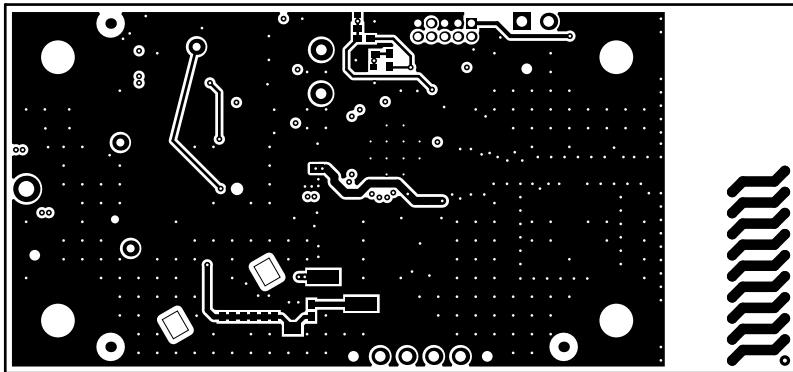
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TID #: TIDA-01476		
PLOT NAME = Top Overlay	GENERATED : 7/19/2017	1:50:54 PM	TEXAS INSTRUMENTS



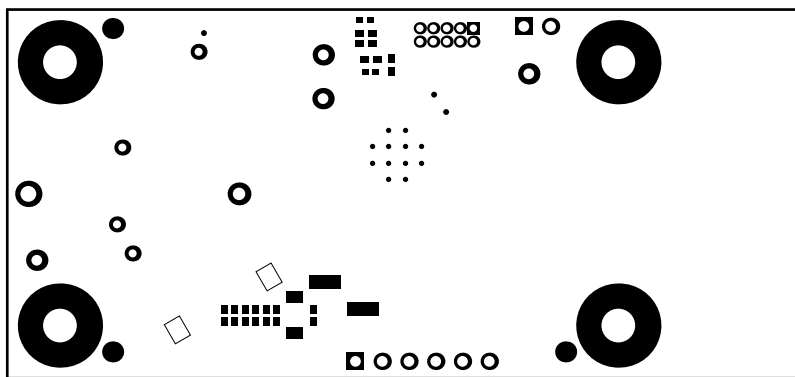
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TID #: TIDA-01476		
PLOT NAME = Top Solder Mask	GENERATED : 7/19/2017 1:50:55 PM	TEXAS INSTRUMENTS	



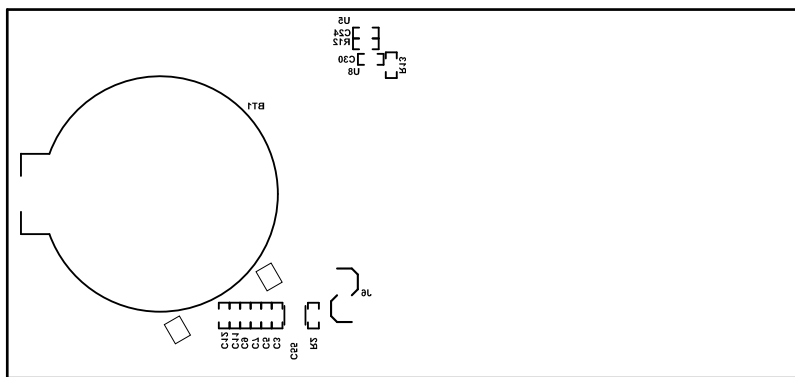
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Layer 1 - Top Layer	TID #: TIDA-01476		
PLOT NAME = Top Layer	GENERATED : 7/19/2017 1:50:56 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Layer 4 - Bottom Layer	TID #: TIDA-01476		
PLOT NAME = Bottom Layer	GENERATED : 7/19/2017 1:50:58 PM	TEXAS INSTRUMENTS	

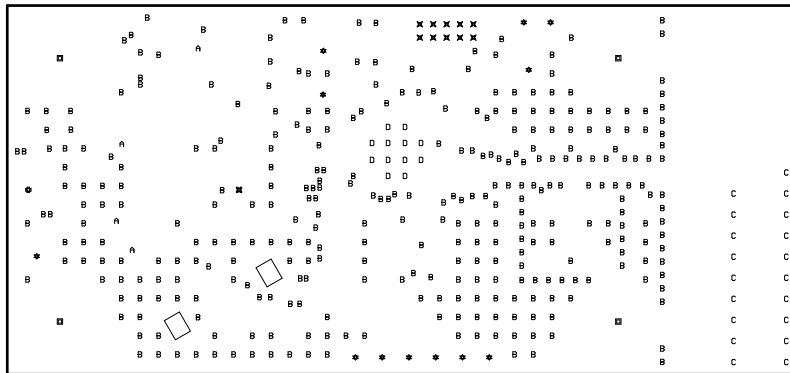


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01476		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/19/2017 1:50:59 PM	TEXAS INSTRUMENTS	

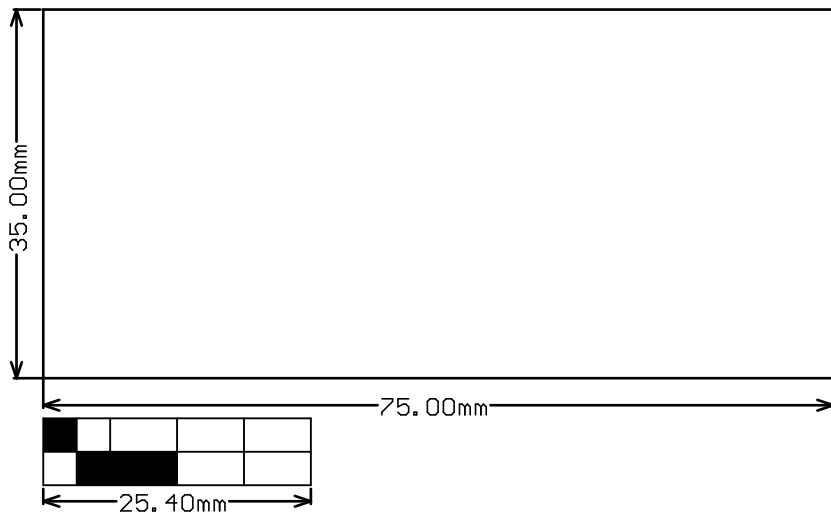


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TID #: TIDA-01476		
PLOT NAME = Bottom Overlay	GENERATED : 7/19/2017	1:51:00 PM	TEXAS INSTRUMENTS

Symbol	Quantity	Finished Hole Size	Plated	Hole Type
D	12	7.87mil (0.200mm)	PTH	Round
B	326	10.00mil (0.254mm)	PTH	Round
C	19	14.96mil (0.380mm)	PTH	Round
✕	10	27.56mil (0.700mm)	PTH	Round
△	4	30.00mil (0.762mm)	PTH	Round
☆	12	40.00mil (1.016mm)	PTH	Round
✖	1	46.50mil (1.181mm)	PTH	Round
⊕	1	59.06mil (1.500mm)	PTH	Round
□	4	125.98mil (3.200mm)	PTH	Round
	389 Total			



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01476		
PLOT NAME = Drill Drawing	GENERATED : 7/19/2017	1:51:02 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01476	REV: A	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01476		
PLOT NAME = Board Dimensions	GENERATED : 7/19/2017	1:51:05 PM	TEXAS INSTRUMENTS

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